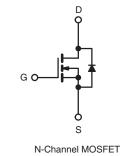




## **E Series Power MOSFET**

| PRODUCT SUMMARY                            |                 |       |  |  |
|--|-----------------|-------|--|--|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 700             |       |  |  |
| R <sub>DS(on)</sub> max. at 25 °C (Ω)      | $V_{GS} = 10 V$ | 0.145 |  |  |
| Q <sub>g</sub> max. (nC)                   | 122             |       |  |  |
| Q <sub>gs</sub> (nC)                       | 21              |       |  |  |
| Q <sub>gd</sub> (nC)                       | 37              |       |  |  |
| Configuration                              | Single          |       |  |  |





#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

| ORDERING INFORMATION            |                |
|---------------------------------|----------------|
| Package                         | TO-220AB       |
| Lead (Pb)-free                  | SiHP24N65E-E3  |
| Lead (Pb)-free and Halogen-free | SiHP24N65E-GE3 |

| <b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted) |                         |                                   |                 |       |      |  |  |
|---|-------------------------|-----------------------------------|-----------------|-------|------|--|--|
| PARAMETER   |                         |                                   | SYMBOL          | LIMIT | UNIT |  |  |
| Drain-Source Voltage  |                         | V <sub>DS</sub>                   | 650             | v     |      |  |  |
| Gate-Source Voltage   |                         |                                   | V <sub>GS</sub> | ± 30  | 1 1  |  |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)                                | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 25 °C            | 1               | 24    |      |  |  |
|   | VGS AL TU V             | $T_C = 100 \ ^\circ C$            |                 | 16    | А    |  |  |
| Pulsed Drain Current <sup>a</sup>   |                         |                                   | I <sub>DM</sub> | 70    |      |  |  |
| Linear Derating Factor  |                         |                                   |                 | 2     | W/°C |  |  |
| Single Pulse Avalanche Energy <sup>b</sup>  |                         | E <sub>AS</sub>                   | 508             | mJ    |      |  |  |
| Maximum Power Dissipation   |                         |                                   | PD              | 250   | W    |  |  |
| Operating Junction and Storage Temperature Range                                  |                         | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150     | °C    |      |  |  |
| Drain-Source Voltage Slope  | T <sub>J</sub> = 125 °C |                                   | -1) / /-14      | 37    |      |  |  |
| Reverse Diode dV/dt <sup>d</sup>  |                         | dV/dt                             | 11              | V/ns  |      |  |  |
| Soldering Recommendations (Peak Temperature) <sup>c</sup>                         | for 10 s                |                                   |                 | 300   | °C   |  |  |

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b.  $V_{DD} = 50$  V, starting  $T_J = 25$  °C, L = 28.2 mH,  $R_g = 25 \Omega$ ,  $I_{AS} = 6$  A.

c. 1.6 mm from case. d.  $I_{SD} \le I_D$ , dl/dt = 100 A/µs, starting  $T_J = 25$  °C.





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|   | 0.0                 |   |  |                            |      |       |       |     |
|---|---------------------|---|--|----------------------------|------|-------|-------|-----|
| PARAMETER   | SYMBOL              | TYP.  |  | MAX.                       |      | UNIT  |       |     |
| Maximum Junction-to-Ambient                               | R <sub>thJA</sub>   | - 62  |  |                            |      | °C/W  |       |     |
| Maximum Junction-to-Case (Drain)                          | R <sub>thJC</sub>   | - 0.5   |  |                            |      | 6/11  |       |     |
| SPECIFICATIONS (T <sub>J</sub> = 25 °C, 1                 | unless otherwi      | se noted)   |  |                            |      |       |       |     |
| PARAMETER   | SYMBOL              | 1   | T CONDIT   | IONS                       | MIN. | TYP.  | MAX.  | UNI |
| Static  |                     |   |  |                            |      |       | I     |     |
| Drain-Source Breakdown Voltage                            | V <sub>DS</sub>     | V <sub>GS</sub> :   | = 0 V, I <sub>D</sub> =  | 250 µA                     | 650  | -     | -     | V   |
| V <sub>DS</sub> Temperature Coefficient                   | $\Delta V_{DS}/T_J$ | Reference to 25 °C, $I_D = 250 \ \mu A$   |  | -                          | 0.72 | -     | V/°(  |     |
| Gate-Source Threshold Voltage (N)                         | V <sub>GS(th)</sub> | V <sub>DS</sub> =   | = V <sub>GS</sub> , I <sub>D</sub> =   | 250 μA                     | 2    | -     | 4     | V   |
|   |                     | $V_{GS} = \pm 20 \text{ V}$   |  | -                          | -    | ± 100 | nA    |     |
| Gate-Source Leakage                                       | I <sub>GSS</sub>    |   | $V_{GS} = \pm 30$  | V                          | -    | -     | ± 1   | μA  |
|   |                     | $V_{DS} = 650 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$  |  |                            | -    | -     | 1     |     |
| Zero Gate Voltage Drain Current                           | I <sub>DSS</sub>    | V <sub>DS</sub> = 520 \   | $V_{DS} = 520 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$ |                            | -    | -     | 10    | μA  |
| Drain-Source On-State Resistance                          | R <sub>DS(on)</sub> | V <sub>GS</sub> = 10 V  |  | <sub>D</sub> = 12 A        | -    | 0.120 | 0.145 | Ω   |
| Forward Transconductance                                  | 9 <sub>fs</sub>     | V <sub>DS</sub> = 8 V, I <sub>D</sub> = 5 A   |  | -                          | 7.1  | -     | S     |     |
| Dynamic   | •                   | •   |  |                            | •    | •     | •     | •   |
| Input Capacitance   | C <sub>iss</sub>    | $V_{GS} = 0 V,$<br>$V_{DS} = 100 V,$<br>f = 1 MHz   |  | -                          | 2740 | -     | pF    |     |
| Output Capacitance  | C <sub>oss</sub>    |   |  | -                          | 122  | -     |       |     |
| Reverse Transfer Capacitance                              | C <sub>rss</sub>    |   |  | -                          | 4    | -     |       |     |
| Effective Output Capacitance, Energy Related <sup>a</sup> | C <sub>o(er)</sub>  | $V_{DS} = 0$ V to 520 V, $V_{GS} = 0$ V   |  | -                          | 93   | -     |       |     |
| Effective Output Capacitance, Time Related <sup>b</sup>   | C <sub>o(tr)</sub>  |   |  | -                          | 352  | -     |       |     |
| Total Gate Charge   | Qq                  |   |  |                            | -    | 81    | 122   | nC  |
| Gate-Source Charge  | Q <sub>gs</sub>     | V <sub>GS</sub> = 10 V  | I <sub>D</sub> = 12  | A, V <sub>DS</sub> = 520 V | -    | 21    | -     |     |
| Gate-Drain Charge   | Q <sub>gd</sub>     |   |  |                            | -    | 37    | -     |     |
| Turn-On Delay Time  | t <sub>d(on)</sub>  |   |  |                            | -    | 24    | 48    | 1   |
| Rise Time   | t <sub>r</sub>      | Vee -   | V <sub>DD</sub> = 520 V, I <sub>D</sub> = 12 A,  |                            | -    | 84    | 126   |     |
| Turn-Off Delay Time                                       | t <sub>d(off)</sub> |   | = 10 V, R <sub>g</sub> :   |                            | -    | 70    | 105   | ns  |
| Fall Time   | t <sub>f</sub>      |   |  | -                          | 69   | 104   | 1     |     |
| Gate Input Resistance                                     | R <sub>g</sub>      | f = 1 MHz, open drain   |  | -                          | 0.68 | -     | Ω     |     |
| Drain-Source Body Diode Characterist                      | cs                  |   |  |                            |      |       |       |     |
| Continuous Source-Drain Diode Current                     | ١ <sub>S</sub>      | MOSFET symbol<br>showing the<br>integral reverse<br>p - n junction diode                                |  | -                          | -    | 24    | A     |     |
| Pulsed Diode Forward Current                              | I <sub>SM</sub>     |   |  | -                          | -    | 70    |       |     |
| Diode Forward Voltage                                     | V <sub>SD</sub>     | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 12 A, V <sub>GS</sub> = 0 V                                    |  | -                          | -    | 1.2   | V     |     |
| Reverse Recovery Time                                     | t <sub>rr</sub>     | $T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 12 \text{ A},$<br>dI/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 25 V |  | -                          | 433  | -     | ns    |     |
| Reverse Recovery Charge                                   | Q <sub>rr</sub>     |   |  | -                          | 7.3  | -     | μΟ    |     |
| Reverse Recovery Current                                  | I <sub>RRM</sub>    |   |  | -                          | 28   | -     | A     |     |

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

b. C<sub>oss(tr)</sub> is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DSS</sub>.



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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

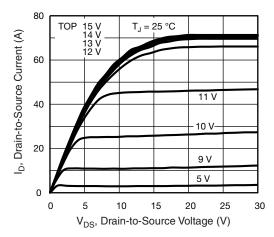


Fig. 1 - Typical Output Characteristics

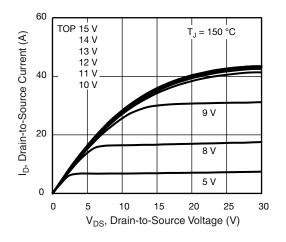
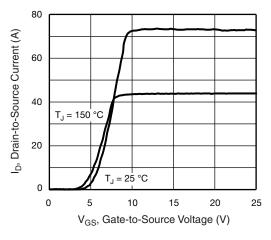


Fig. 2 - Typical Output Characteristics





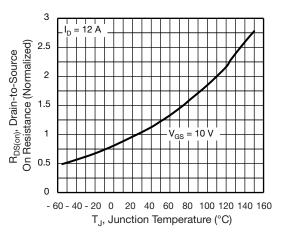


Fig. 4 - Normalized On-Resistance vs. Temperature

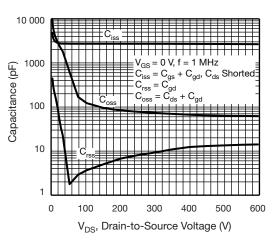
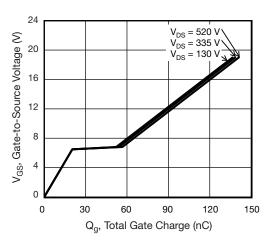


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





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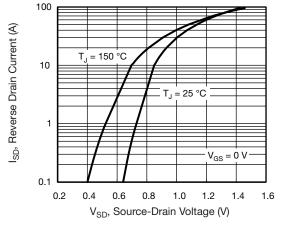


Fig. 7 - Typical Source-Drain Diode Forward Voltage

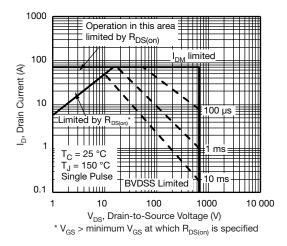


Fig. 8 - Maximum Safe Operating Area

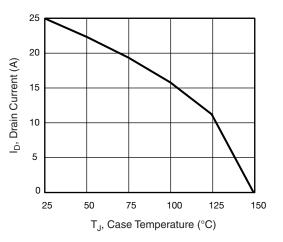


Fig. 9 - Maximum Drain Current vs. Case Temperature

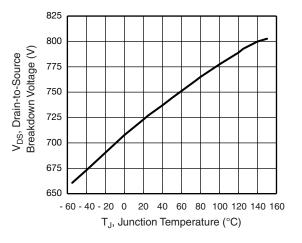
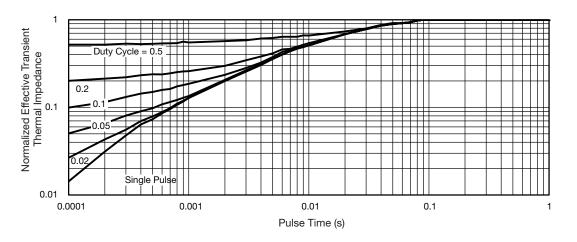


Fig. 10 - Temperature vs. Drain-to-Source Voltage





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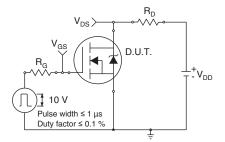


Fig. 12 - Switching Time Test Circuit

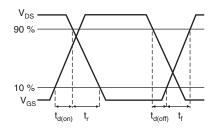


Fig. 13 - Switching Time Waveforms

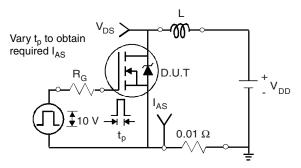


Fig. 14 - Unclamped Inductive Test Circuit

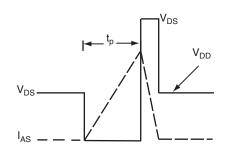
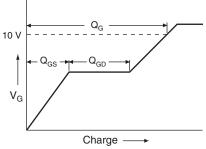


Fig. 15 - Unclamped Inductive Waveforms



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Fig. 16 - Basic Gate Charge Waveform

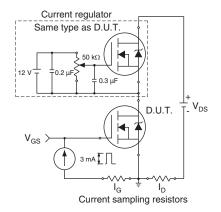


Fig. 17 - Gate Charge Test Circuit

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#### Peak Diode Recovery dV/dt Test Circuit

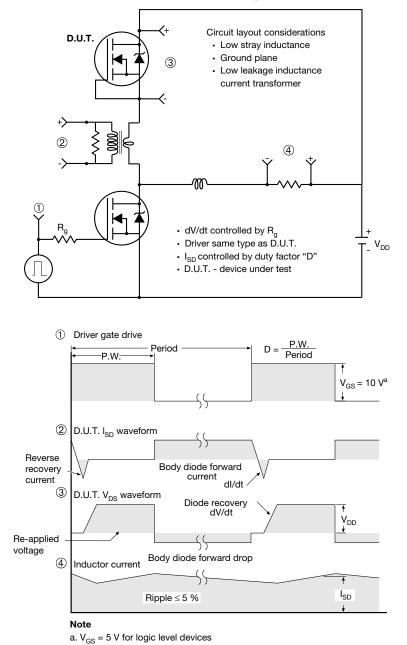


Fig. 18 - For N-Channel

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